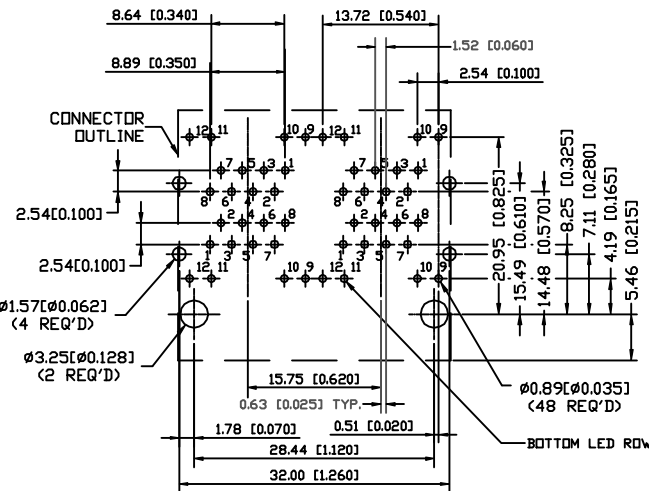
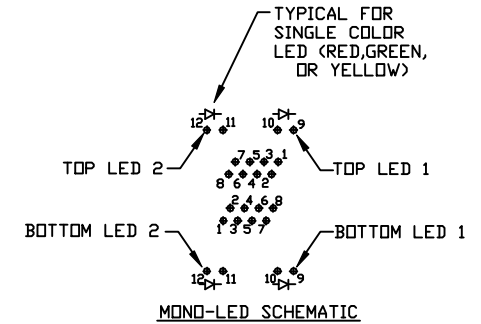
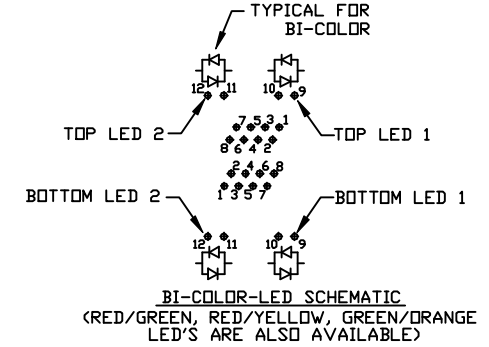
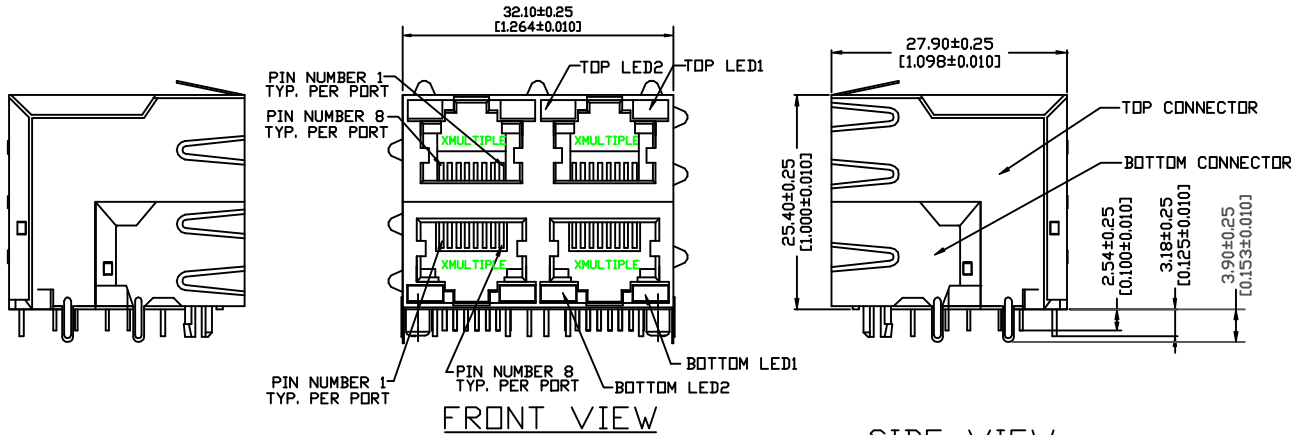


REVISIONS					
ECO	ZONE	REV	DESCRIPTION	DATE	APPROVED
		J1	REVISED RELEASE	07/31/01	Chen



**SUGGESTED PCB LAYOUT**  
(COMPONENT SIDE)

1. MATERIALS:  
HOUSING: HIGH TEMP. THERMOPLASTIC, BLACK, UL 94V-0  
CONTACTS: 0.014 INCHES (0.35 MILLIMETERS) THICK PHOSPHOR BRONZE PLATED WITH 150 MICROINCHES (3.81 MICROMETERS) MINIMUM THICK TIN LEAD IN SOLDER AREA. 15 MICROINCHES (0.38 MICROMETERS) MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE CONTACTS PLATED WITH 50 MICROINCHES (1.27 MICROMETERS) MINIMUM THICK NICKEL.  
SHIELDED: 0.0098 INCHES (0.25 MILLIMETERS) THICK COPPER ZINC ALLOY PLATED WITH 30 MICROINCHES (0.762 MICROMETERS) MINIMUM THICK NICKEL.

2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F

3. PART NUMBER: XRJD-S-22-8-8-X

REFER TO LED OPTIONS TABLE FOR ORDERING CODES

NOTES: UNLESS OTHERWISE SPECIFIED  
UNSPECIFIED TOLERANCE: .X(± 0.010)(0.25)  
.x ± 0.008(0.15)

XMULTIPLE		CONNECTING THE INFORMATION AGE	
XMULTIPLE ASIA 11P-1, No. 70, P.O. Box-Hsing W. Road Taipei, Taiwan, R.O.C.	XMULTIPLE USA 3050 Old County Road Menlo Park, CA 94025	DOC: P00284-XRJD21	REV: VIQ
THIS DRAWING IS A CONTROLLED DOCUMENT.		DRW: C. TSAI	DATE: 07/31/01
TITLE: Stacked RJ45 Connectors, W/LED, 8P, 8C, Shielded, Thru Hole, 2 Piece Structure		PART NO: XRJD-S-22-8-8-X	
DIMENSIONS [mm]/inch		SHEET 1 of 1	REV J1